



PRODUCT BULLETIN

Standard Flex

Double Layer

Flexible Circuit Interconnect

Layers

- 2-layer

Base Material

- Polyimide - 50 μ (.002") flame retardant (FR) or non-flame retardant polyester epoxy adhesive
- Polyester - 75 μ (.003") or 125 μ (.005") FR or non-FR polyester epoxy adhesive
- PEN - 50 μ (.002") non-FR polyester epoxy adhesive

Copper

- 1 oz/ft² - 35 μ (.0014") Base copper: 2 oz/ft² - 70 μ (.0028") Finished thickness
- 2 oz/ft² - 70 μ (.0028") Base copper: 3 oz/ft² - 105 μ (.0042") Finished thickness

Soldermask/Dielectric

- Screen Printed Ink
- Photoimaged coverlay
- Polyimide film - 25 μ (.001")
- Polyester film - 75 μ (.003")

Surface Finish

- Antitarnish
- *Shelcoat*[®] - OSP - organic solderability preservative
- Tin/lead - electroplated
- Tin/lead - Hot air solder leveled (HASL)
- Nickel/Gold - electroplated

Conductor Width and Space

- 2 oz/ft² - 70 μ (.0028") Finished thickness - .305mm (.012") minimum
- 3 oz/ft² - 105 μ (.0042") Finished thickness - .500mm (.020") minimum

Soldermask/Dielectric Definition

- See Sheldahl Standard Flexible Circuit Design Guideline

Via Holes/Pad Size

- .50mm (.016") finished hole size minimum {.46mm (.018") punched hole size}.
- 1.4mm (.054") pad size minimum or oversized from punched hole by .018" per side

Design Capability

- Sheldahl has a extensive design capability. Design data and net lists can be input and output in a wide variety of standard industry formats

Prototype Capability

- Sheldahl has a fully staffed prototype facility that will provide prototypes in 2-3 weeks

